



## 40V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

# **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> T <sub>C</sub> = +25°C (Note 9)
40V	$3.3 \text{m}\Omega$ @ V <sub>GS</sub> = 10V	100A
40 V	5.0mΩ @ V <sub>GS</sub> = 5V	95A

# **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- BLDC motors
- DC-DC converters
- Load switches

# **Features**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable And Robust End Application
- Low R<sub>DS(ON)</sub> Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH43M8LPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

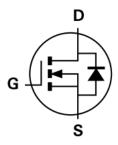
https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

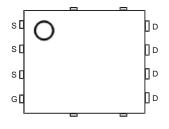
- Package: PowerDI<sup>®</sup>5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)

### Site1:





Internal Schematic



Top View Pin Configuration

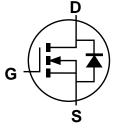
### Site2:

PowerDI5060-8 (SWP) (Type UX)

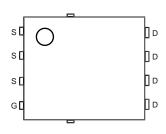


Top View

Bottom View



Internal Schematic



Top View Pin Configuration

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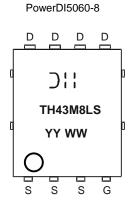
# **Ordering Information** (Note 4)

Part Number	Pookaga	Packing		
Part Number	Package	Qty.	Carrier	
DMTH43M8LPSQ-13	PowerDI5060-8	2,500	Tape & Reel	
DMTH43M8LPSQ-13	PowerDI5060-8 (SWP) (Type UX)	2,500	Tape & Reel	

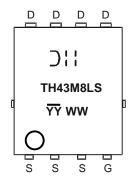
Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

# **Marking Information**



### PowerDI5060-8 (SWP) (Type UX)



☐ I = Manufacturer's Marking
TH43M8LS = Product Type Marking Code
YYWW or YYWW = Date Code Marking
YY or YY = Year Code (ex: 22 = 2022)
WW = Week Code (01 to 53)



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	40	V	
Gate-Source Voltage		$V_{GSS}$	±20	V
Continuous Drain Current, VGS = 10V (Note 5)	T <sub>A</sub> = +25°C T <sub>A</sub> = +100°C	lo	22 15.5	А
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 6) (Note 9)	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	lo	100 82	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	350	А	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	69	А	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle	I <sub>SM</sub>	350	А	
Avalanche Current, L = 1mH	las	13.2	Α	
Avalanche Energy, L = 1mH	Eas	87	mJ	

# **Thermal Characteristics**

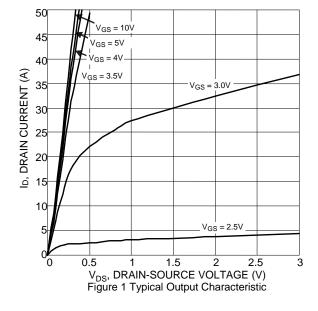
Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	$P_{D}$	2.7	W
Thermal Resistance, Junction to Ambient (Note 5)		Reja	55	°C/W
Total Power Dissipation (Note 6)	Tc = +25°C	PD	83	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	1.8	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

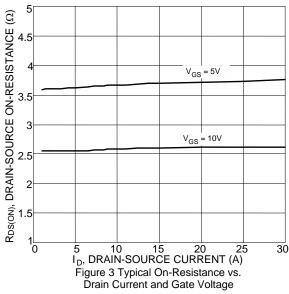
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

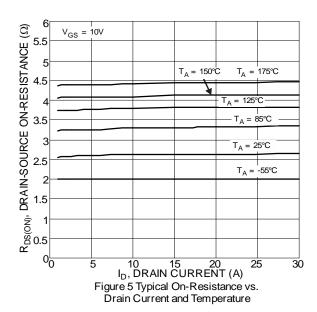
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V <sub>DS</sub> = 32V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	IGSS		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	2.5	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain Source On Registeres (To. 195°C)	Dagger	1	2.7	3.3	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance (T <sub>C</sub> = +25°C)	Rds(on)		3.6	5.0	11177	V <sub>G</sub> S = 5V, I <sub>D</sub> = 15A	
Static Drain-Source On-Resistance (T <sub>C</sub> = +175°C) (Note 8)	RDS(ON)	_	4.7	_	mΩ	V <sub>G</sub> S = 10V, I <sub>D</sub> = 20A	
Diode Forward Voltage	VsD	_	_	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 20A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	1	2,693	3,367		\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Output Capacitance	Coss	1	850	1105	pF	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz	
Reverse Transfer Capacitance	Crss		52	104			
Gate Resistance	Rg	_	2.54	5.1	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	Q <sub>G</sub>	_	38.5	49			
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	17.6	22	nC	V <sub>DS</sub> = 20V, I <sub>D</sub> = 20A	
Gate-Source Charge	Qgs	_	6.9	11	nC		
Gate-Drain Charge	Q <sub>GD</sub>	_	6.9	11			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	5.2	10			
Turn-On Rise Time	t <sub>R</sub>		5.7	11		$V_{DD} = 20V, V_{GS} = 10V,$ $I_{D} = 20A, R_{G} = 1.6\Omega$	
Turn-Off Delay Time	tD(OFF)	_	23.5	46	ns		
Turn-Off Fall Time	t <sub>F</sub>		11	22			
Body Diode Reverse Recovery Time	trr		35.4	70	ns	150 1716 10007	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>		32.9	_	nC	I <sub>F</sub> = 15A, di/dt = 100A/μs	

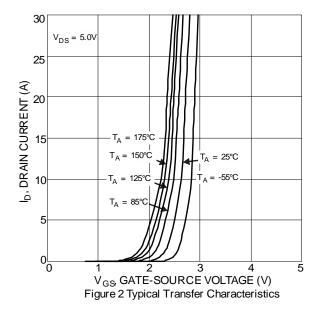
 Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.
 Package limit. Notes:

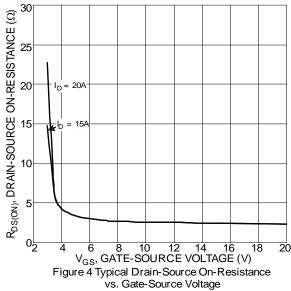












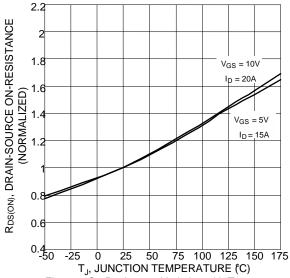


Figure 6 On-Resistance Variation with Temperature





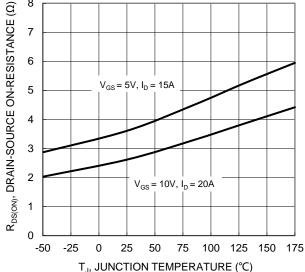
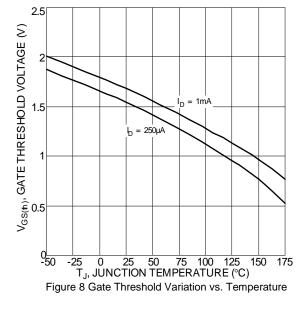
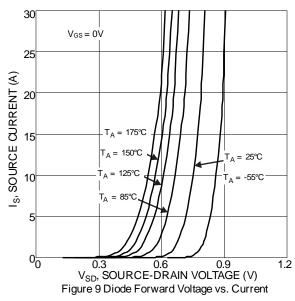


Figure 7. On-Resistance Variation with Temperature





 $V_{GS}(V)$  $V_{DS} = 20V, I_{D} = 20A$ Qg (nC) Figure 11. Gate Charge

f = 1MHzC<sub>T</sub>, JUNCTION CAPACITANCE (pF)  $C_{iss}$  $\mathsf{C}_{\mathsf{rss}}$ V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 10. Typical Junction Capacitance

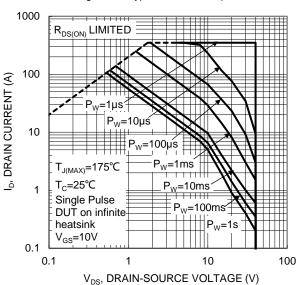
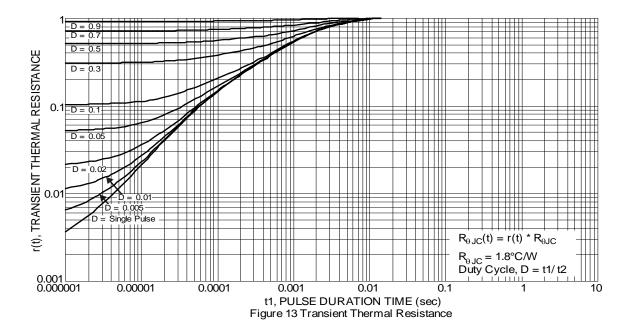


Figure 12. SOA, Safe Operation Area





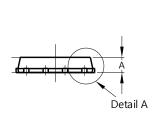


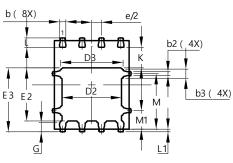
# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### Site1

# Detail A 0(4X)



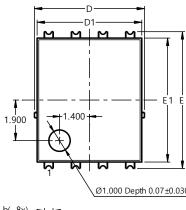


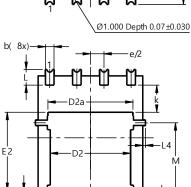
PowerDI5060-8

PowerDI5060-8				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
<b>A</b> 1	0.00	0.05	_	
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D	į.	5.15 BSC	;	
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
Е	•	6.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е	1.27 BSC			
G	0.51	0.71	0.61	
K	0.51	-	-	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
M	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
Θ	10°	12°	11°	
Θ1	6°	8°	7°	
All Dimensions in mm				

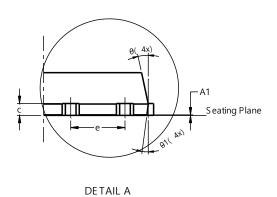
### Site2

# PowerDI5060-8 (SWP) (Type UX)





-b4( 8x)



DETAIL A

PowerDI5060-8 (SWP)				
(Type UX)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4		).25REF		
С	0.230	0.330	0.277	
D	5	.15 BS0	)	
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	.40 BS0	)	
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е	1	.27BSC	;	
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L1a	0.050REF			
L4	0.025	0.225	0.125	
M	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

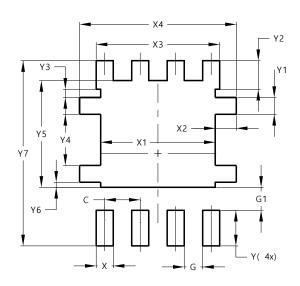


# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### Site1:

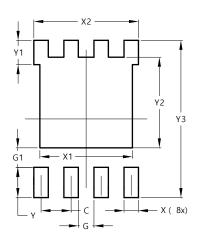
### PowerDI5060-8



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
Х	0.610
X1	4.100
X2	0.755
Х3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

### Site2:

# PowerDI5060-8 (SWP) (Type UX)



Di	Value
Dimensions	(in mm)
С	1.270
G	0.660
G1	0.820
Х	0.610
X1	4.100
X2	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610



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